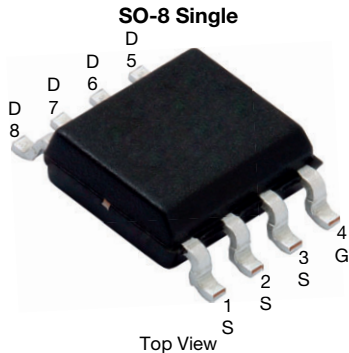


## N-Channel 250 V (D-S) MOSFET



Marking code: 4848A

PRODUCT SUMMARY	
$V_{DS}$ (V)	250
$R_{DS(on)}$ max. ( $\Omega$ ) at $V_{GS} = 10$ V	0.150
$R_{DS(on)}$ max. ( $\Omega$ ) at $V_{GS} = 7.5$ V	0.170
$Q_g$ typ. (nC)	8.6
$I_D$ (A) <sup>d</sup>	4.1
Configuration	Single

### FEATURES

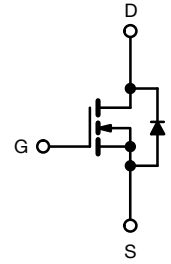
- ThunderFET® power MOSFET
- 100 %  $R_g$  tested
- Material categorization for definitions of compliance please see [www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)



RoHS  
COMPLIANT  
HALOGEN  
FREE

### APPLICATIONS

- DC/DC converters
- Boost converters
- LED backlighting
- PD switch
- Load switch



N-Channel MOSFET

ORDERING INFORMATION	
Package	SO-8
Lead (Pb)-free and halogen-free	Si4434ADY-T1-GE3

ABSOLUTE MAXIMUM RATINGS ( $T_A = 25$ °C, unless otherwise noted)			
PARAMETER	SYMBOL	LIMIT	UNIT
Drain-source voltage	$V_{DS}$	250	V
Gate-source voltage	$V_{GS}$	$\pm 20$	
Continuous drain current ( $T_J = 150$ °C)	$I_D$	$T_C = 25$ °C	4.1
		$T_C = 70$ °C	3.3
		$T_A = 25$ °C	2.8 <sup>a, b</sup>
		$T_A = 70$ °C	2.3 <sup>a, b</sup>
Pulsed drain current ( $t = 100$ $\mu$ s)	$I_{DM}$	25	A
Continuous source-drain diode current	$I_S$	$T_C = 25$ °C	
		$T_A = 25$ °C	2.4 <sup>a, b</sup>
Single pulse avalanche current	$I_{AS}$	12	mJ
Single pulse avalanche energy	$E_{AS}$	7.2	
Maximum power dissipation	$P_D$	$T_C = 25$ °C	6
		$T_C = 70$ °C	3.8
		$T_A = 25$ °C	2.9 <sup>a, b</sup>
		$T_A = 70$ °C	1.9 <sup>a, b</sup>
Operating junction and storage temperature range	$T_J, T_{stg}$	-55 to +150	°C

THERMAL RESISTANCE RATINGS				
PARAMETER	SYMBOL	TYPICAL	MAXIMUM	UNIT
Maximum junction-to-ambient <sup>a, c</sup>	$R_{thJA}$	36	43	°C/W
Maximum junction-to-foot (drain)	$R_{thJF}$	16	21	

#### Notes

- Surface mounted on 1" x 1" FR4 board
- $t = 10$  s
- Maximum under steady state conditions is 84 °C/W
- $T_C = 25$  °C



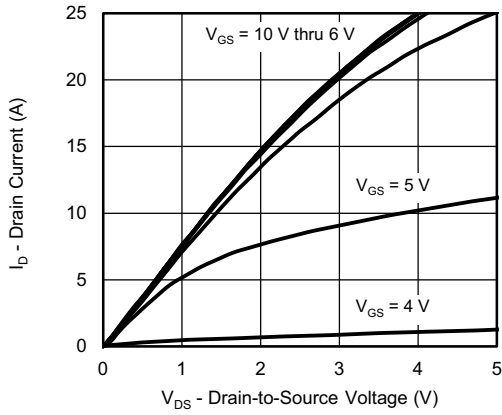
SPECIFICATIONS ( $T_J = 25\text{ }^\circ\text{C}$ , unless otherwise noted)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
<b>Static</b>						
Drain-source breakdown voltage	$V_{DS}$	$V_{GS} = 0\text{ V}$ , $I_D = 250\text{ }\mu\text{A}$	250	-	-	V
$V_{DS}$ temperature coefficient	$\Delta V_{DS}/T_J$	$I_D = 250\text{ }\mu\text{A}$	-	254	-	mV/ $^\circ\text{C}$
$V_{GS(th)}$ temperature coefficient	$\Delta V_{GS(th)}/T_J$		-	-6.9	-	
Gate-source threshold voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}$ , $I_D = 250\text{ }\mu\text{A}$	2	-	4	V
Gate-source leakage	$I_{GSS}$	$V_{DS} = 0\text{ V}$ , $V_{GS} = \pm 20\text{ V}$	-	-	$\pm 100$	nA
Zero gate voltage drain current	$I_{DSS}$	$V_{DS} = 250\text{ V}$ , $V_{GS} = 0\text{ V}$	-	-	1	$\mu\text{A}$
		$V_{DS} = 250\text{ V}$ , $V_{GS} = 0\text{ V}$ , $T_J = 70\text{ }^\circ\text{C}$	-	-	10	
On-state drain current <sup>a</sup>	$I_{D(on)}$	$V_{DS} \leq 10\text{ V}$ , $V_{GS} = 10\text{ V}$	10	-	-	A
Drain-source on-state resistance <sup>a</sup>	$R_{DS(on)}$	$V_{GS} = 10\text{ V}$ , $I_D = 2.8\text{ A}$	-	0.125	0.150	$\Omega$
		$V_{GS} = 7.5\text{ V}$ , $I_D = 2.7\text{ A}$	-	0.135	0.170	
Forward transconductance <sup>a</sup>	$g_{fs}$	$V_{DS} = 10\text{ V}$ , $I_D = 2.8\text{ A}$	-	10	-	S
<b>Dynamic <sup>b</sup></b>						
Input capacitance	$C_{ISS}$	$V_{DS} = 125\text{ V}$ , $V_{GS} = 0\text{ V}$ , $f = 1\text{ MHz}$	-	600	-	pF
Output capacitance	$C_{OSS}$		-	65	-	
Reverse transfer capacitance	$C_{RSS}$		-	2	-	
Total gate charge	$Q_g$	$V_{DS} = 125\text{ V}$ , $V_{GS} = 10\text{ V}$ , $I_D = 2\text{ A}$	-	10.9	16.5	nC
		$V_{DS} = 125\text{ V}$ , $V_{GS} = 7.5\text{ V}$ , $I_D = 2\text{ A}$	-	8.6	12.9	
Gate-source charge	$Q_{gs}$		-	2.7	-	
Gate-drain charge	$Q_{gd}$		-	2.9	-	
Output charge	$Q_{OSS}$	$V_{DS} = 125\text{ V}$ , $V_{GS} = 0\text{ V}$	-	30	45	
Gate resistance	$R_g$	$f = 1\text{ MHz}$	0.5	2.3	4.6	$\Omega$
Turn-on delay time	$t_{d(on)}$	$V_{DD} = 125\text{ V}$ , $R_L = 54.4\text{ }\Omega$ , $I_D \cong 2.3\text{ A}$ , $V_{GEN} = 10\text{ V}$ , $R_g = 1\text{ }\Omega$	-	8	16	ns
Rise time	$t_r$		-	22	35	
Turn-off delay time	$t_{d(off)}$		-	18	30	
Fall time	$t_f$		-	22	35	
Turn-on delay time	$t_{d(on)}$	$V_{DD} = 125\text{ V}$ , $R_L = 54.4\text{ }\Omega$ , $I_D \cong 2.3\text{ A}$ , $V_{GEN} = 7.5\text{ V}$ , $R_g = 1\text{ }\Omega$	-	10	20	
Rise time	$t_r$		-	22	40	
Turn-off delay time	$t_{d(off)}$		-	18	30	
Fall time	$t_f$		-	25	50	
<b>Drain-Source Body Diode Characteristics</b>						
Continuous source-drain diode current	$I_S$	$T_C = 25\text{ }^\circ\text{C}$	-	-	5	A
Pulse diode forward current	$I_{SM}$		-	-	25	
Body diode voltage	$V_{SD}$	$I_S = 2.3\text{ A}$ , $V_{GS} = 0\text{ V}$	-	0.8	1.2	V
Body diode reverse recovery time	$t_{rr}$	$I_F = 2.3\text{ A}$ , $di/dt = 100\text{ A}/\mu\text{s}$ , $T_J = 25\text{ }^\circ\text{C}$	-	100	150	ns
Body diode reverse recovery charge	$Q_{rr}$		-	356	550	nC
Reverse recovery fall time	$t_a$		-	65	-	ns
Reverse recovery rise time	$t_b$		-	35	-	

**Notes**

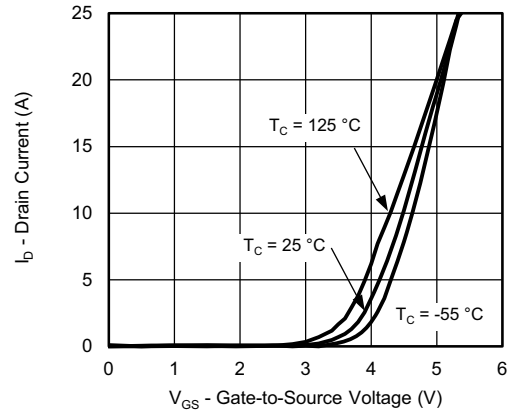
- a. Pulse test; pulse width  $\leq 300\text{ }\mu\text{s}$ , duty cycle  $\leq 2\%$   
b. Guaranteed by design, not subject to production testing

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

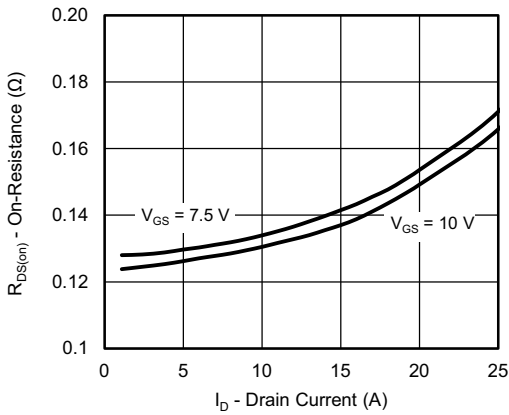
**TYPICAL CHARACTERISTICS** (25 °C, unless otherwise noted)



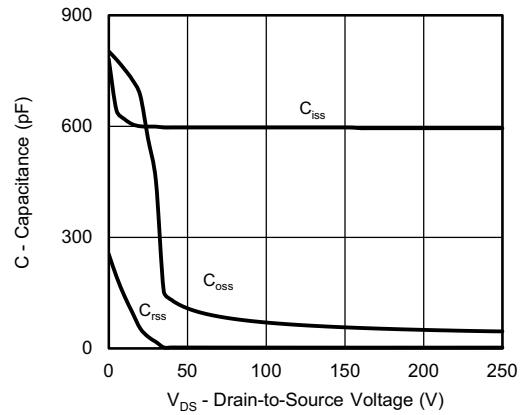
**Output Characteristics**



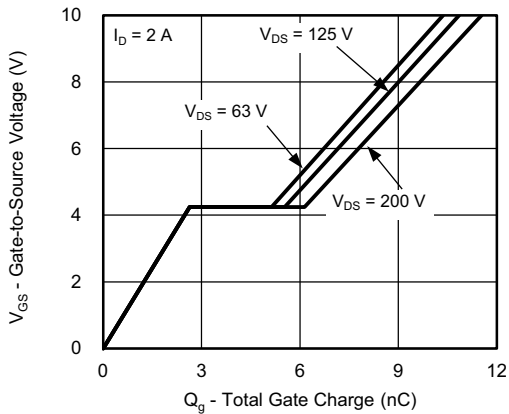
**Transfer Characteristics**



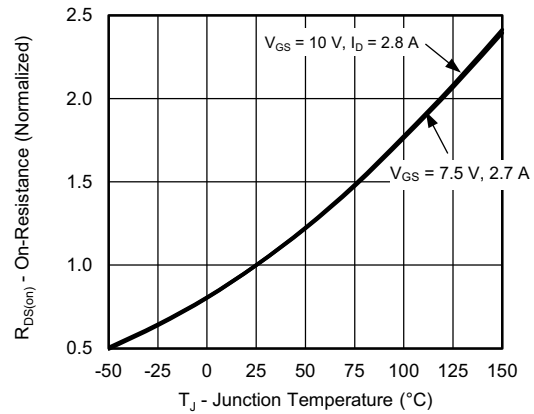
**On-Resistance vs. Drain Current and Gate Voltage**



**Capacitance**



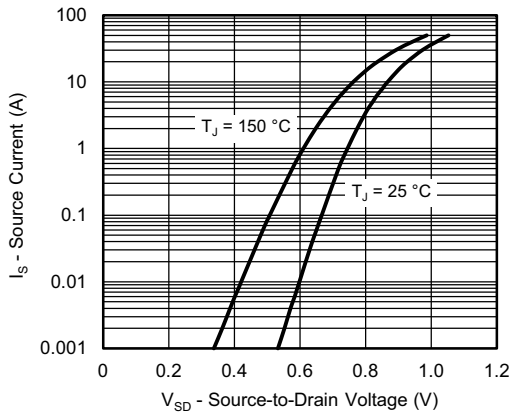
**Gate Charge**



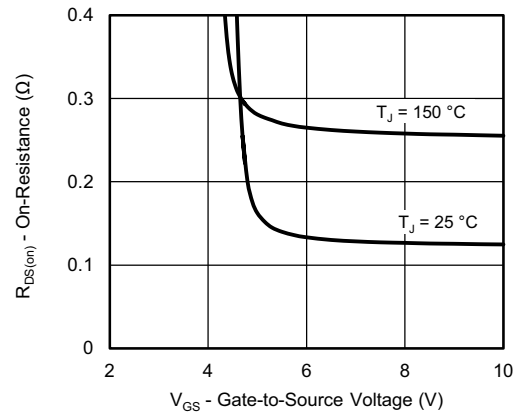
**On-Resistance vs. Junction Temperature**



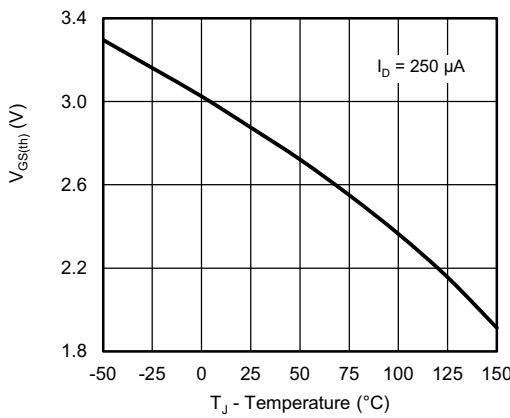
**TYPICAL CHARACTERISTICS** (25 °C, unless otherwise noted)



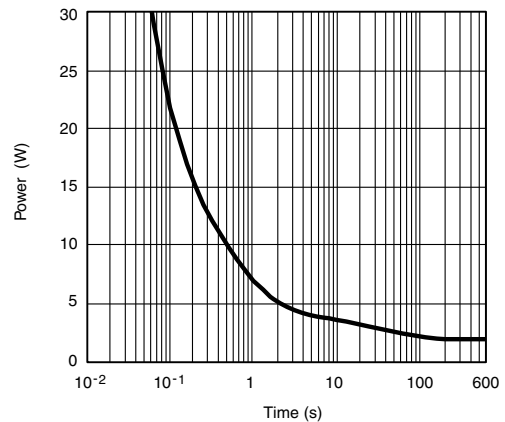
**Source-Drain Diode Forward Voltage**



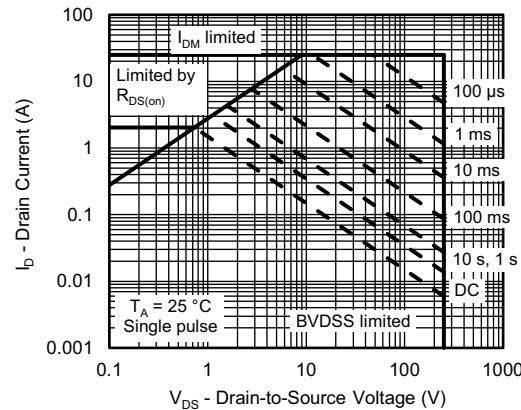
**On-Resistance vs. Gate-to-Source Voltage**



**Threshold Voltage**



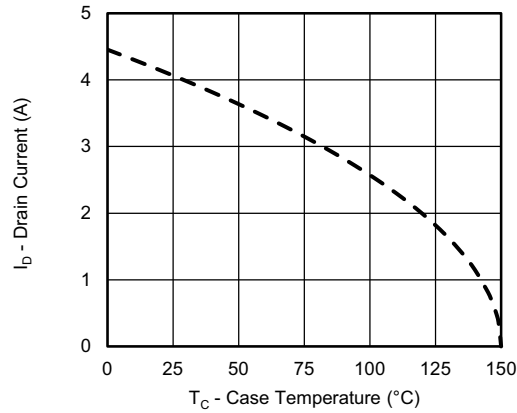
**Single Pulse Power, Junction-to-Ambient**



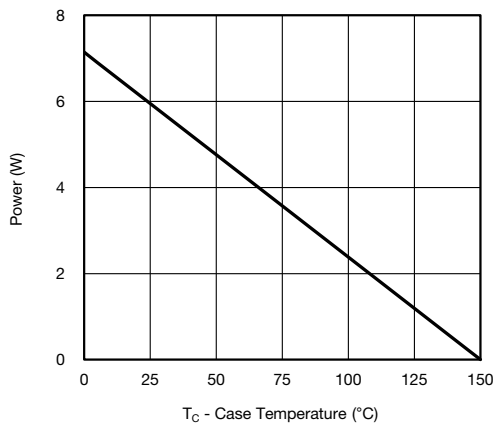
**Safe Operating Area, Junction-to-Ambient**



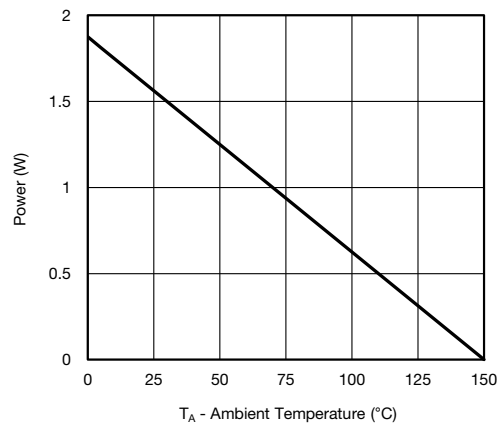
**TYPICAL CHARACTERISTICS** (25 °C, unless otherwise noted)



**Current Derating <sup>a</sup>**



**Power, Junction-to-Case**



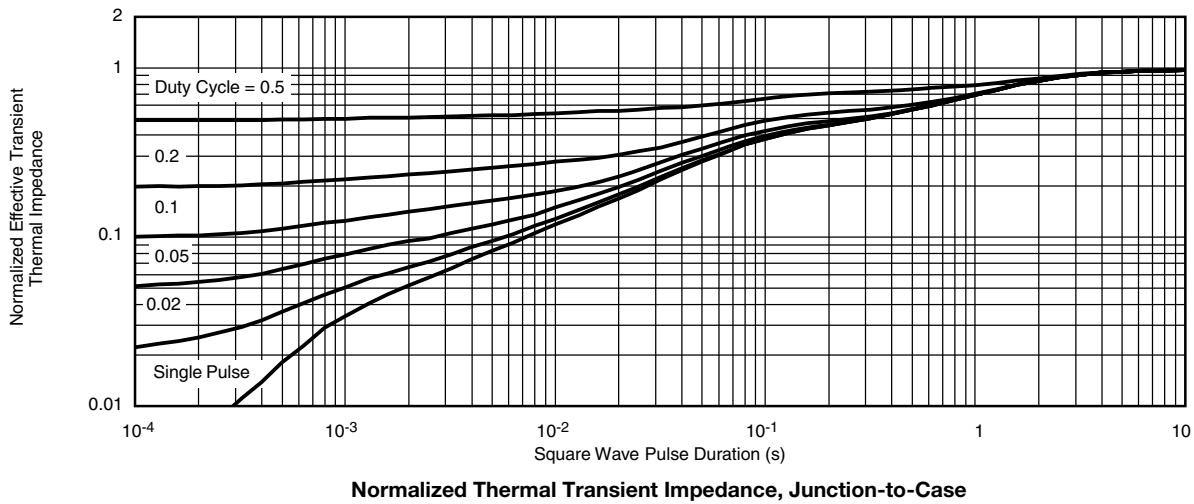
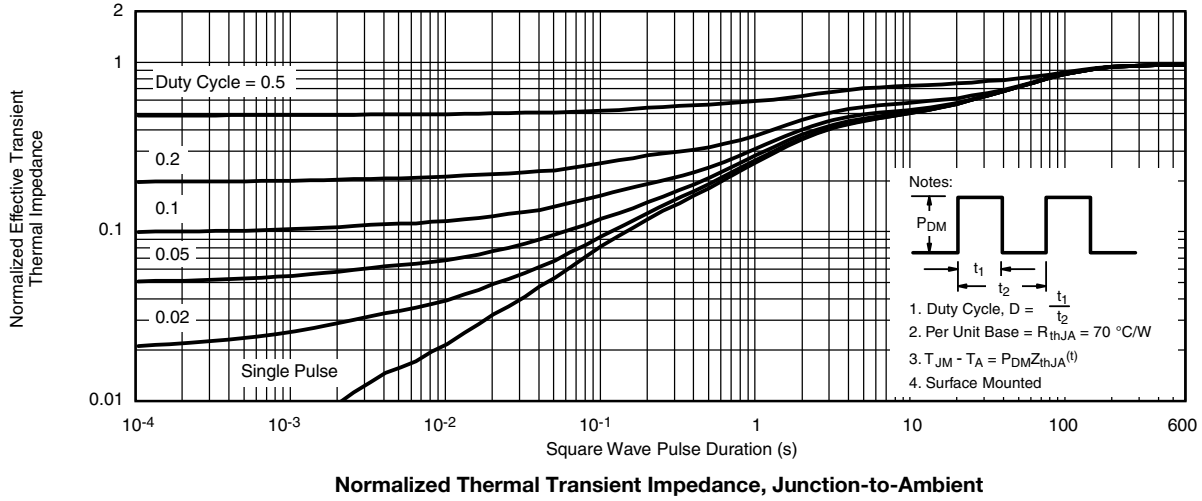
**Power, Junction-to-Ambient**

**Note**

- a. The power dissipation  $P_D$  is based on  $T_J$  max. = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit



**TYPICAL CHARACTERISTICS** (25 °C, unless otherwise noted)



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